

Features	Specifications
Host Interface	<ul style="list-style-type: none"> - PCIe 4.0 x4 (Bandwidth: 16GT/s x4) - Backward compatible with existing PCIe generation transfer rates - Compliance with PCI Express Base Specification Revision 4.0 - Compliance with NVMe 2.0 - Host Memory Buffer (HMB) support
Processor	<ul style="list-style-type: none"> - Dual-CPU architecture with built-in ARM Cortex R5 - TSMC 12nm processing technology with Automotive Service Package (ASP)
Flash Controller	<ul style="list-style-type: none"> - Up to 4 Channels with 16 Chip Enable (CE) counts - Flash transfer rate up to 2400MT/s - Support 3D TLC and QLC NAND flash memory - Compliant with Toggles 5.0 and ONFI 5.0 - Flash I/O operating voltage supply 1.2V
Data Reliability	<ul style="list-style-type: none"> - Phison 5th generation LDPC ECC & RAID ECC engine - SmartECC (RAID ECC) engine - End-To-End Data Path Protection
Security	<ul style="list-style-type: none"> - AES 256 - SHA 512 - RSA 4096 - TCG OPAL - DICE
Performance	<ul style="list-style-type: none"> - Sequential read up to 7000MB/s - Sequential write up to 7000MB/s - 4K Random read up to 1000K IOPS - 4K Random write up to 1000K IOPS
Temperature Range	<ul style="list-style-type: none"> - Operating range: -40~95 °C - Storage range: -40~145 °C
Package	<ul style="list-style-type: none"> - 529-ball FCCSP, 12 mm x 12 mm
Peripheral	<ul style="list-style-type: none"> - Built-in internal thermal sensor - GPIO pins - Built-in UART function - I3C and SPI for external ROM
Highlights	<ul style="list-style-type: none"> - Designed for ASIL-B compliance - SR-IOV supported - With dual-port functionality - Can fit into the design of BGA 1620; also available in discrete (packaged) form